



TEAM PHANTOM

SFU FORMULA SAE ELECTRIC













BSPD REV1







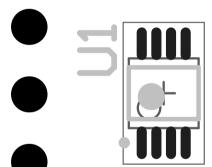




























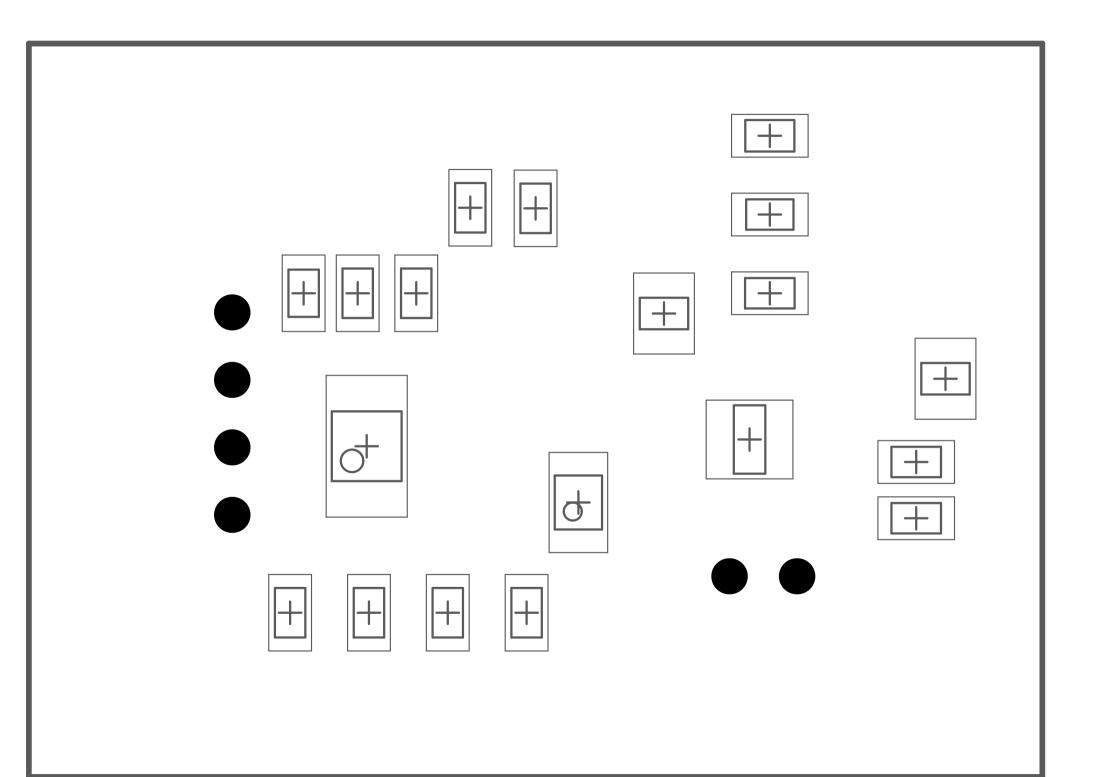






Faraz Borghei





Design Rules Verification Report

Warnings 0 Rule Violations 0 Waived Violations 10

Warnings Total 0

Rule Violations	
Clearance Constraint (Gap=0.254mm) (All),(All)	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Un-Routed Net Constraint ((All))	0
Un-Connected Pin Constraint ((Disabled)(All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.2mm) (Max=1mm) (Preferred=0.254mm) (All)	0
Power Plane Connect Rule(Relief Connect)(Expansion=0.508mm) (Conductor Width=0.254mm)	0
Hole Size Constraint (Min=0.025mm) (Max=5mm) (All)	0
Hole To Hole Clearance (Gap=0.254mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.1mm) (All),(All)	0
Silk To Solder Mask (Clearance=0.2mm) (IsPad),(All)	0
Silk to Silk (Clearance=0.254mm) (All),(All)	0
Net Antennae (Tolerance=0mm) (All)	0
Height Constraint (Min=0mm) (Max=25.4mm) (Prefered=12.7mm) (All)	0
Total	0

Waived Violations	
Minimum Solder Mask Sliver (Gap=0.1mm) (All),(All)	10
Total	10

Minimum Solder Mask Sliver (Gap=0.1mm) (All),(All)

Minimum Solder Mask Sliver Constraint: (0.097mm < 0.1mm) Between Pad U2-1(31.25mm,21.7mm) on Top Layer And Pad Minimum Solder Mask Sliver Constraint: (0.097mm < 0.1mm) Between Pad U2-2(30.6mm,21.7mm) on Top Layer And Pad Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U3-1(26.05mm,10.65mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U3-2(26.55mm,10.65mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U3-3(27.05mm,10.65mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U3-5(27.55mm,13.75mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U3-6(27.05mm,13.75mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U3-7(26.55mm,13.75mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U4-1(42.45mm,16.575mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U4-2(43.1mm,16.575mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U4-2(43.1mm,16.575mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U4-2(43.1mm,16.575mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U4-2(43.1mm,16.575mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U4-2(43.1mm,16.575mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U4-2(43.1mm,16.575mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U4-2(43.1mm,16.575mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U4-2(43.1mm,16.575mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U4-2(43.1mm,16.575mm) on Top Layer And Minimum Solder Mask Sliver Constraint: (0.047mm < 0.1mm) Between Pad U4-2(43.1mm,16.575mm) on To